TL080 JFET-INPUT OPERATIONAL AMPLIFIER

7

6

П СОМР

] v_{cc+}

OUT

OFFSET N2

P PACKAGE (TOP VIEW)

N1/COMP

IN- **□** 2

IN+ 3

 V_{CC}

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- Low Power Consumption
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Output Short-Circuit Protection
- Low Total Harmonic Distortion . . . 0.003% Typ
- High Input Impedance . . . JFET Input Stage
- External Frequency Compensation
- Common-Mode Input Voltage Range Includes V_{CC+}
- Latch-Up-Free Operation
- High Slew Rate . . . 13 V/μs Typ

description

The TL080 JFET-input operational amplifier incorporates well-matched, high-voltage JFET and bipolar transistors in an integrated circuit. This device features high slew rates, low input bias and offset currents, and a low offset-voltage temperature coefficient. Offset adjustment and external-compensation options are available.

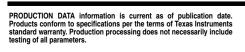
The TL080C is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

		PACKAGE
TA	V _{IO} max AT 25°C	PLASTIC DIP (P)
0°C to 70°C	10 mV	TL080CP



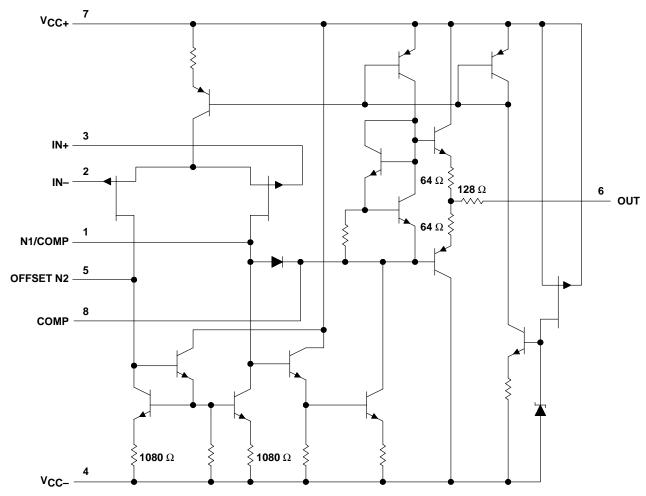
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schematic



All component values shown are nominal.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage (see Note 1): V _{CC+}		. 18 V
V _{CC}		–18 V
Differential input voltage, V _{ID} (see Note 2)		±30 V
Input voltage, V _I (see Notes 1 and 3)		±15 V
Duration of short-circuit current (see Note 4)	Ur	nlimited
Package thermal impedance, θ _{JA} (see Notes 5 and 6)	8	35°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds		260°C
Storage temperature range, T _{stg}	–65°C to	150°C

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. Differential voltages are at IN+ with respect to IN-.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - 4. The output can be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics, $V_{CC\pm} = \pm 15 \text{ V}$ (unless otherwise noted)

	PARAMETER	TEST CONDITI	ONS	T _A †	MIN	TYP	MAX	UNIT
\/	Input offset voltage	V _O = 0, R _S =	- 50 O	25°C		3	15	mV
VIO		VO = 0, KS =	= 50 Ω	Full range			20	IIIV
$\alpha_{ m V_{IO}}$	Temperature coefficient of input offset voltage	$V_O = 0$, $R_S =$	= 50 Ω	Full range		18		μV/°C
		V- 0		25°C		5	200	pА
IIO	Input offset current [‡]	VO = 0		Full range			2	nA
lin	lanut bias sumant	Vo = 0		25°C		30	400	pА
lΒ	Input bias current [‡]	VO = 0		Full range			10	nA
VICR	Common-mode input voltage range			25°C	±11	-12 to 15		٧
	Maximum peak output voltage swing	R _L = 10 kΩ		25°C	±12	±13.5		
V_{OM}		$R_L \ge 10 \text{ k}\Omega$		Full range	±12			V
		$R_L \ge 2 k\Omega$	±10		±12			
۸. ۰۰	Large-signal differential voltage amplification	$V_O = \pm 10 \text{ V}, R_L \ge 2 \text{ k}\Omega$		25°C	25	200		V/mV
AVD	Large-signal differential voltage amplification	VO = ±10 V, KL 2	Full range	15				
B ₁	Unity-gain bandwidth			25°C		3		MHz
rį	Input resistance			25°C		10 ¹²		Ω
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min,$ $V_{O} = 0, R_{S} = 50 \Omega$	1	25°C	70	86		dB
k _{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC} = \pm 15 \text{ V to } \pm 9$ $V_{O} = 0, R_{S} = 50 \Omega$		25°C	70	86		dB
Icc	Supply current	$V_O = 0$, No lo	oad	25°C		1.4	2.8	mA
V _{O1} /V _{O2}	Crosstalk attenuation	A _{VD} = 100		25°C		120		dB

[†] All characteristics are measured under open-loop conditions with zero common-mode voltage unless otherwise specified. Full range for T_A is -40°C to 85°C.

[‡] Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 5. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

operating characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C

	PARAMETER	MIN	TYP	MAX	UNIT			
SR	Slew rate at unity gain	V _I = 10 V,	$R_L = 2 k\Omega$, $C_L = 100 pF$, Se	ee Figure 1	8	13		V/μs
Γ	Rise-time overshoot factor)/ ₂ 00 m)/	$R_{I} = 2 k\Omega$, $C_{I} = 100 pF$, Se	Coo Figure 1		0.05		μs
t _r Rise-time overshoot factor		$V_{I} = 20 \text{ mV},$	KL = 2 KS2, CL = 100 pr, 30	ee rigule i		20%		
V Favivalent input paige velter		$R_S = 100 \Omega$	f = 1 kHz			18		nV/√ Hz
V _n	Equivalent input noise voltage	KS = 100 22	f = 10 Hz to 10 kHz			4		μV
In	Equivalent input noise current	$R_S = 100 \Omega$,	f = 1 kHz			0.01		pA/√ Hz
THD	Total harmonic distortion	$V_{O(rms)} = 10 V,$	$R_S \le 1 \text{ k}\Omega$, $R_L \ge 2 \text{ k}\Omega$, $f =$	= 1 kHz	0	.003%	·	-

APPLICATION INFORMATION

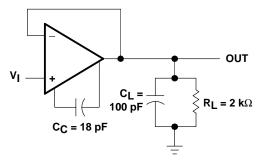


Figure 1. Unity-Gain Amplifier

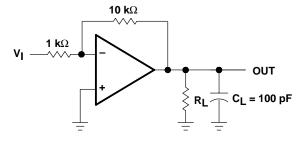


Figure 2. Gain-of-10 Inverting Amplifier

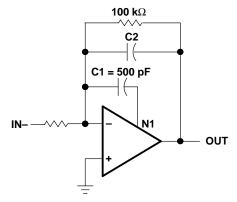


Figure 3. Feed-Forward Compensation

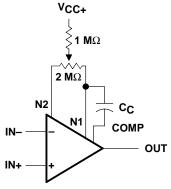


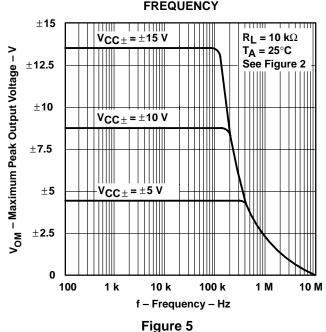
Figure 4. Input Offset Voltage Null Circuit

Table of Graphs

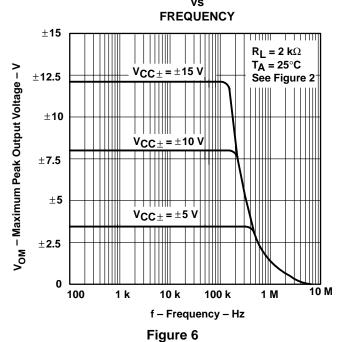
			FIGURE
Vом	Maximum peak output voltage	vs Frequency vs Free-air temperature vs Load resistance vs Supply voltage	5, 6, 7 8 9 10
Large-signal differential voltage amplification		vs Free-air temperature vs Frequency	11 12
	Differential voltage amplification	vs Frequency	13
PD	Total power dissipation	vs Free-air temperature	14
lcc	Supply current	vs Free-air temperature vs Supply voltage	14 15
I _{IB}	Input bias current	vs Free-air temperature	16
	Large-signal pulse response	vs Time	17
VO	Output voltage	vs Elapsed time	18
CMRR	Common-mode rejection ratio	vs Free-air temperature	19
V _n	Equivalent input noise voltage	vs Frequency	20
THD	Total harmonic distortion	vs Frequency	21

MAXIMUM PEAK OUTPUT VOLTAGE

FREQUENCY

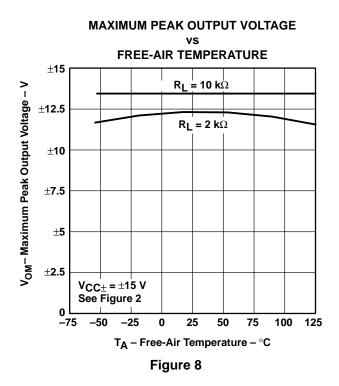


MAXIMUM PEAK OUTPUT VOLTAGE



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MAXIMUM PEAK OUTPUT VOLTAGE vs **FREQUENCY** ±15 $V_{CC\pm} = \pm 15 V$ V_{OM} - Maximum Peak Output Voltage - V $R_L = 2 k\Omega$ T_A = 25°C ±12.5 See Figure 2 ±10 T_A = -55°C ± 7.5 T_A = 125°C ± 5 ± 2.5 10 k 40 k 100 k 400 k 1 M 4 M 10 M f - Frequency - Hz Figure 7



MAXIMUM PEAK OUTPUT VOLTAGE vs

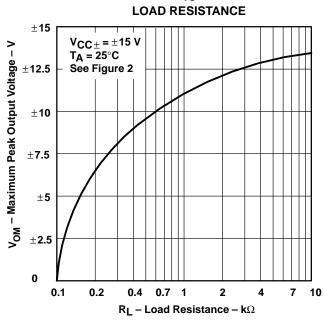


Figure 9

MAXIMUM PEAK OUTPUT VOLTAGE vs

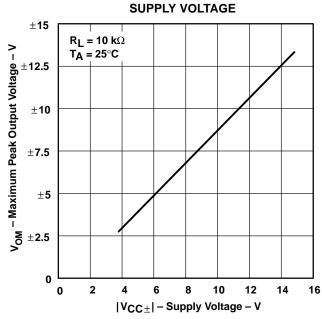
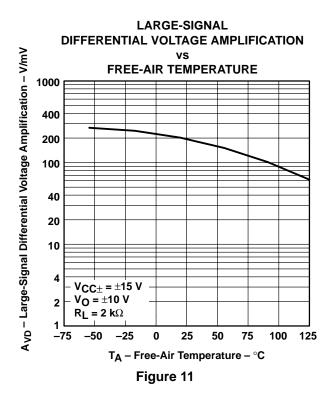
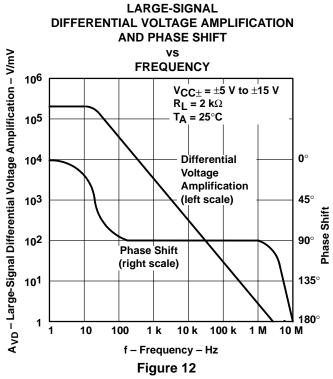
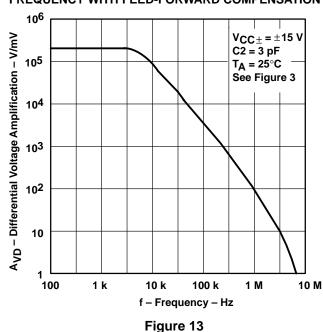


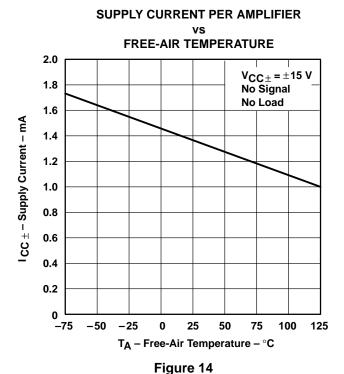
Figure 10

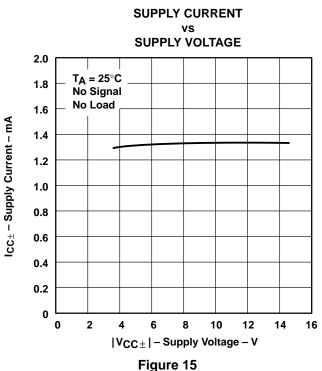




DIFFERENTIAL VOLTAGE AMPLIFICATION vs FREQUENCY WITH FEED-FORWARD COMPENSATION

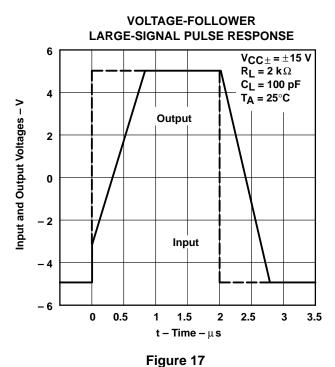






INPUT BIAS CURRENT FREE-AIR TEMPERATURE 100 $V_{CC\pm} = \pm 15 V$ I_{IB} - Input Bias Current - nA 10 0.1 0.01 - 25 - 50 25 50 75 100 125 T_A - Free-Air Temperature - °C

Figure 16



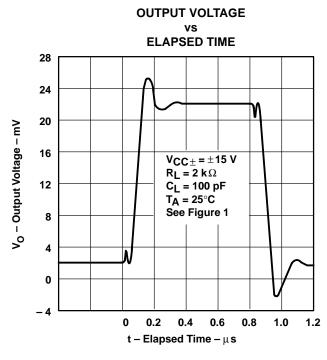
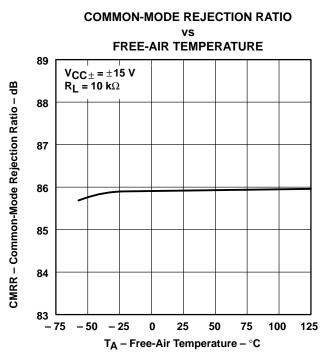


Figure 18



FREQUENCY THAN Noise VOLTAGE VS FREQUENCY VCC± = ±15 V AVD = 10 RS = 1000Ω TA = 25°C

400 1 k

f - Frequency - Hz

4 k 10 k

40 k 100 k

Figure 19 Figure 20

TOTAL HARMONIC DISTORTION

0

10

40 100

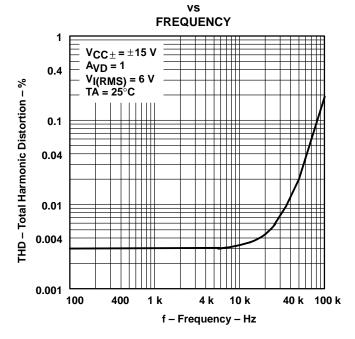


Figure 21

APPLICATION INFORMATION

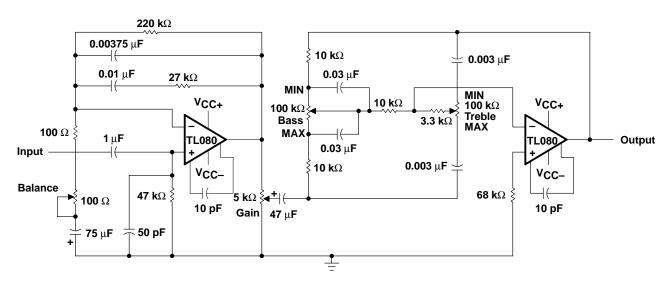


Figure 22. IC Preamplifier





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
TL080CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL080CPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL080IP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

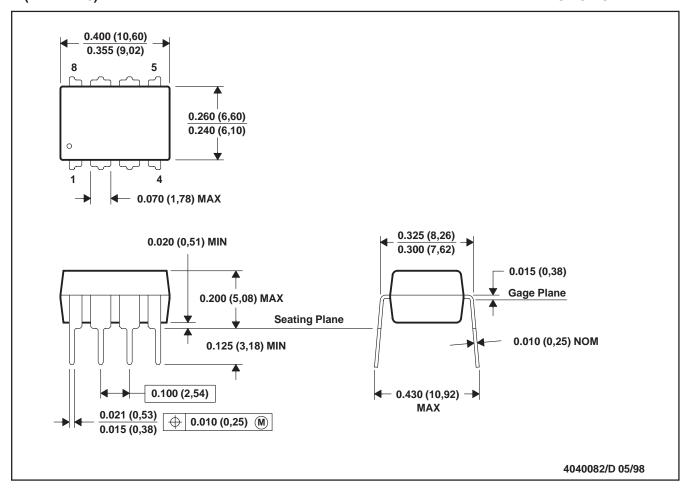
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm



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